

DESCRIPTION

The ICPL0530 and ICPL0531 dual channel devices each consists of an infrared emitting diode optically coupled to a high speed photo detector transistor. Separate connection for the photodiode and output transistor collector increases the speed by several order of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor.

These devices belong to Isocom Compact Range of optocouplers.

FEATURES

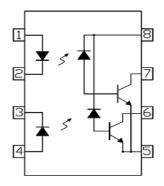
- High speed 1Mbit/s
- Half Pitch 1.27mm
- High AC Isolation Voltage 3750V_{RMS}
- Guaranteed Performance from 0°C to 70°C
- Wide Operating Temperature Range
- -55°C to 100°C
- Pb Free and RoHS Compliant
- Safety Approvals Pending

APPLICATIONS

- Line Receivers, Data Communication
- Telecommunication Equipments
- Power Transistor Isolation in Motor Drives
- Replacement of Low Speed Phototransistor Optocouplers
- Switch Mode Power Supplies
- High Speed Logic Ground Isolation
- Home Appliances

ORDER INFORMATION

Available in Tape and Reel with 2000pcs per reel





- 1 Anode (Channel 1)
- 2 Cathode (Channel 1)
- 3 Cathode (Channel 2)
- 4 Cathode (Channel 2)
- 5 GND
- 6 Output (Channel 2)
- 7 Output (Channel 1)

100mW

 V_{CC}

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device.

Exposure to absolute maximum ratings for long periods of time

Input

Forward Current	25mA
Peak Forward Current (50% Duty Cycle, 1ms P.W.)	50mA
Peak Transient Current (≤1µs P.W., 300pps)	1A
Reverse Voltage	5V
Power dissipation	45mW

Output

Output Current	8mA
Peak Output Current	16mA
Output Voltage	-0.5 to 20V
Supply Voltage	-0.5 to 30V
Base-Emitter Reverse Voltage	5V

Total Package

Power Dissipation

Isolation Voltage	$3750V_{\text{RMS}}$
Operating Temperature	-55 to 100 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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ELECTRICAL CHARACTERISTICS (T_A = 0°C to 70°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	V_{F}	$I_F = 16mA$		1.4	1.8	V
Reverse Voltage	V_R	$I_R = 10\mu A$	5.0			V
Temperature Coefficient of V_F	$\Delta V_F/\Delta T_A$	$I_F = 16mA$		-1.6		mV/°C
Input Capacitance	C_{IN}	$V_F = 0V$, $f = 1MHz$		60		pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
High Level Supply Current	I_{CCH}	$I_F = 0mA$, $V_{CC} = 15V$, $V_O = Open$, $T_A = 25$ °C		0.01	1	μA
		$I_F = 0$ mA, $V_{CC} = 15$ V, $V_O = O$ pen			2	
Low Level Supply Current	I_{CCL}	$I_F = 16\text{mA}, V_{CC} = 15\text{V}$ $V_O = \text{Open}$		120	200	μA



ELECTRICAL CHARACTERISTICS ($T_A = 0$ °C to 70°C unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current Transfer Ratio	CTR	ICPL0530				%
		$V_{CC} = 4.5V,$ $I_{F} = 16\text{mA}, V_{O} = 0.4V$ $T_{A} = 25 ^{\circ}\text{C}$	7		50	
		$V_{CC} = 4.5V,$ $I_F = 16\text{mA}, V_O = 0.5V$	5			
		ICPL0531				
		$V_{CC} = 4.5V,$ $I_F = 16\text{mA}, V_O = 0.4V$ $T_A = 25 ^{\circ}\text{C}$	19		50	
		$V_{CC} = 4.5V,$ $I_F = 16\text{mA}, V_O = 0.5V$	15			
High Level Output Current	I_{OH}	$V_{CC} = 5.5V, V_{O} = 5.5V$ $I_{F} = 0mA, T_{A} = 25 °C$		0.001	0.5	μА
		$V_{CC} = 15V, V_{O} = 15V$ $I_{F} = 0mA, T_{A} = 25 °C$		0.01	1	
		$V_{CC} = 15V, V_{O} = 15V$ $I_{F} = 0mA$			50	
Low Level Output Voltage	$V_{ m OL}$	ICPL0530				V
Output voltage		$V_{CC} = 4.5V,$ $I_{F} = 16\text{mA}, I_{O} = 1.1\text{mA}$ $T_{A} = 25 ^{\circ}\text{C}$		0.18	0.4	
		$V_{CC} = 4.5V$, $I_F = 16\text{mA}$, $I_O = 0.8\text{mA}$			0.5	
		ICPL0531		0.2	0.4	
		$V_{CC} = 4.5V,$ $I_F = 16mA, I_O = 3mA$ $T_A = 25 °C$		0.3	0.4	
		$V_{CC} = 4.5V,$ $I_F = 16mA, I_O = 2.4mA$			0.5	



ELECTRICAL CHARACTERISTICS (T_A = 0°C to 70°C unless otherwise specified)

Switching Characteristics ($T_A = 0$ °C to 70°C, $I_F = 16$ mA, $V_{CC} = 5$ V unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Propagation Delay Time	T_{PHL}	ICPL0530				μs
to Logic Low		$R_L = 4.1k\Omega$, $T_A = 25$ °C			1.5	
		$R_L = 4.1k\Omega$			2.0	
		ICPL0531				1
		$R_{L} = 1.9k\Omega, T_{A} = 25^{\circ}C$			0.8	
		$R_{\rm L} = 1.9 {\rm k}\Omega$			1.0	
Propagation Delay Time to Logic High	T_{PLH}	ICPL0530				μs
to Logic High		$R_L = 4.1k\Omega, T_A = 25^{\circ}C$			1.5	
		$R_{\rm L} = 4.1 {\rm k}\Omega$			2.0	
		ICPL0531				1
		$R_{L} = 1.9k\Omega, T_{A} = 25^{\circ}C$			0.8	
		$R_{\rm L} = 1.9 k\Omega$			1.0	
Common Mode	CM _H	ICPL0530	1000	10000		V/µs
Transient Immunity at Logic High		$I_F = 0mA, R_L = 4.1k\Omega,$ $V_{CM} = 10Vp-p,$ $T_A = 25^{\circ}C$				
		ICPL0531	1000			1
		$I_F = 0 mA, R_L = 1.9 k\Omega,$ $V_{CM} = 1500 Vp-p,$ $T_A = 25^{\circ}C$				
Common Mode	CM_L	ICPL0530	1000	10000		V/µs
Transient Immunity at Logic Low		$I_F = 16\text{mA}, R_L = 4.1\text{k}\Omega,$ $V_{CM} = 10\text{Vp-p},$ $T_A = 25^{\circ}\text{C}$				
		ICPL0531	1000			1
		$I_F = 16\text{mA}, R_L = 350\Omega,$ $V_{CM} = 1500\text{Vp-p},$ $T_A = 25^{\circ}\text{C}$				

 CM_H – The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., $V_{OUT} > 2.0V$).



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}$ C unless otherwise specified)

ISOLATION

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Insulation Voltage	$V_{\rm ISO}$	AC 1 minute, RH 40 to 60%	3750			V_{RMS}
		Input Leads Shorted together and Output Leads Shorted together				



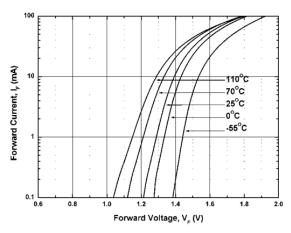


Fig 1 Forward Current vs Forward Voltage

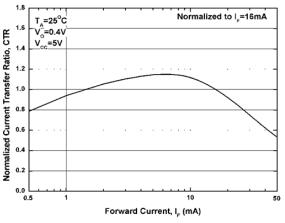


Fig 3 Current Transfer Ratio vs forward Current

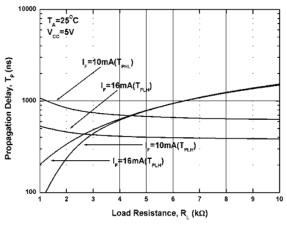


Fig 5 Propagation Delay vs Load Resistance

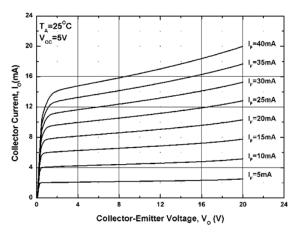


Fig 2 Output Current vs Output voltage

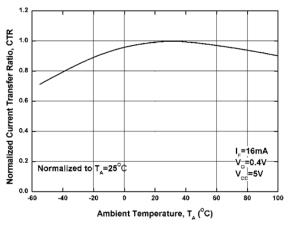


Fig 4 Current Transfer Ratio vs T_A

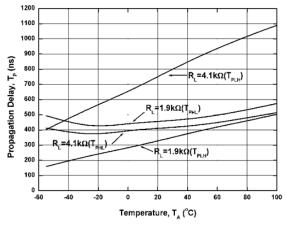


Fig 6 Propagation Delay vs TA



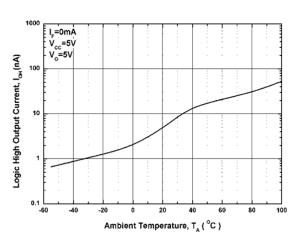


Fig 7 Logic High Output Current vs T_A

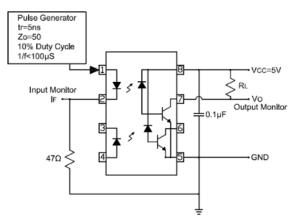
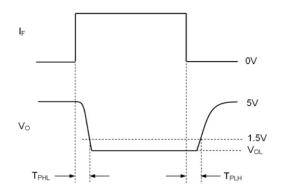


Fig 8 Switching Time Test Circuit



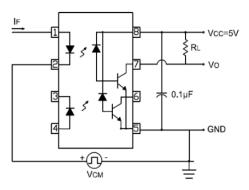
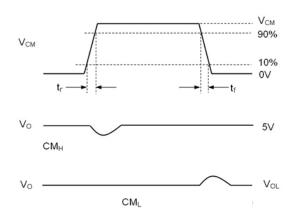


Fig 9 Transient Immunity Test Circuit

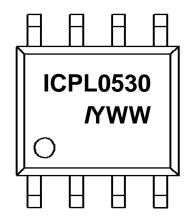




ORDER INFORMATION

ICPL0530, ICPL0531					
After PN	PN PN Description Packing quantity				
None	ICPL0530, ICPL0531	Surface Mount Tape & Reel	2000 pcs per reel		

DEVICE MARKING



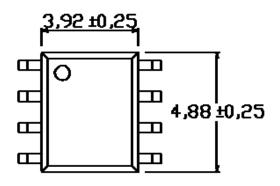
ICPL0530 denotes Device Part Number (ICPL0530 is used as example)

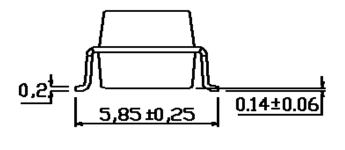
denotes Isocom

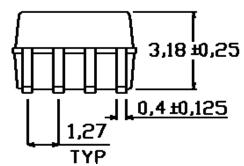
Y denotes 1 digit Year code WW denotes 2 digit Week code



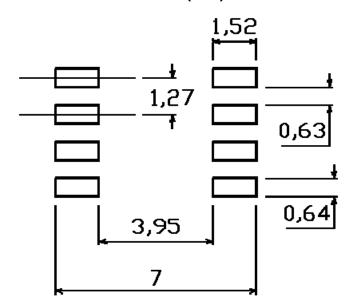
PACKAGE DIMENSIONS (mm)





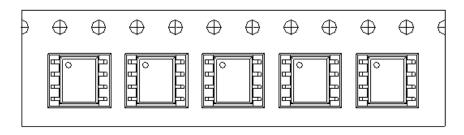


RECOMMENDED PAD LAYOUT (mm)



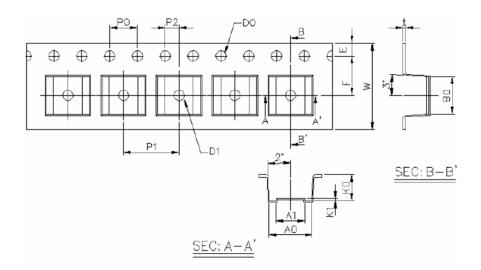


TAPE AND REEL PACKAGING





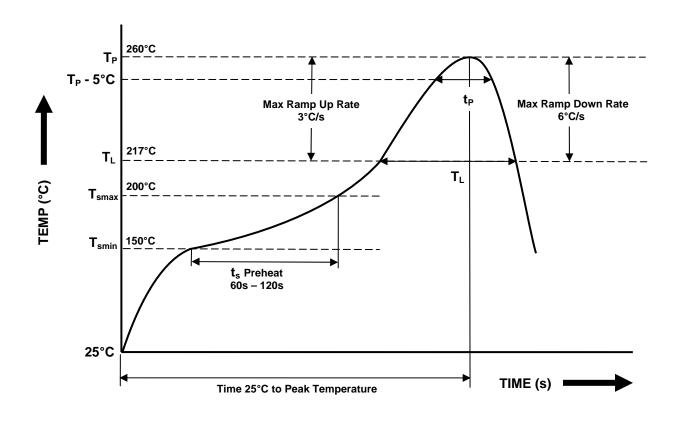
Direction of feed from reel



Dimension No.	Α0	A 1	В0	D0	D1	E	F
Dimension (mm)	6.2±0.1	4.1±0.1	5.28±0.1	1.5±0.1	1.5±0.3	1.75±0.1	5.5±0.1
Dimension No.	Ро	P1	P2	t	w	K0	K1
Dimension (mm)	4.0±0.1	8.0±0.1	2.0±0.1	0.4±0.1	12.0 +0.3/-0.1	3.7±0.1	0.3±0.1



IR REFLOW SOLDERING TEMPERATURE PROFILE (One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T _{SMIN}) - Max Temperature (T _{SMAX}) - Time T _{SMIN} to T _{SMAX} (t _s)	150°C 200°C 60s - 120s
$\begin{tabular}{lll} \textbf{Soldering Zone} \\ - & \mbox{Peak Temperature } (T_P) \\ - & \mbox{Liquidous Temperature } (T_L) \\ - & \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P = 5^{\circ}\mbox{C}) \\ - & \mbox{Time maintained above } T_L \ (t_L) \\ - & \mbox{Ramp Up Rate } (T_L \ \mbox{to } T_P) \\ - & \mbox{Ramp Down Rate } (T_P \ \mbox{to } T_L) \\ \end{tabular}$	260°C 217°C 30s 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.



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